

Amendments to the Claims

Please cancel claims 1-56, 103 and 104 without prejudice or disclaimer.

Please add new claims 148-159.

The listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-147. (Canceled)

148. (New) An apparatus configured as a light emitting diode light source, said apparatus comprising:

- a) a plurality of light emitting diodes being capable of emitting light when supplied with adequate electrical current;
- b) a first substrate portion upon which each of said plurality of light emitting diodes are mounted, said first substrate portion being electrically conductive and thermally conductive;
- c) a second substrate portion connected to the first substrate portion, said second substrate portion being thermally conductive and electrically insulating;
- d) a heat pipe capable of transferring heat from one location to another, said heat pipe having a first end portion and a second end portion, said first end portion being thermally connected to the second substrate portion;
- e) a heat sink constructed of a material capable of dissipating heat into a heat dissipation environment, said heat sink being thermally coupled to the second end portion of the heat pipe; and
- f) control circuitry capable of controlling electrical current transmission to said plurality of light emitting diodes in order to control light production by said plurality of light emitting diodes;

wherein heat generated by the plurality of light emitting diodes is transmitted to the heat sink via the first substrate portion, the second substrate portion and the heat pipe.

149. (New) The apparatus according to claim 148, wherein the first substrate portion is configured with a plurality of cups therein, at least some of the cups being sized and configured to have one or more light emitting diodes positioned therein.
150. (New) The apparatus according to claim 148, wherein each of the plurality of light emitting diodes are unpackaged.
151. (New) The apparatus according to claim 148, wherein each of the plurality of light emitting diodes comprises a bottom surface having a plurality of material layers formed thereon, said bottom surface configured as a heat transfer surface.
152. (New) The apparatus according to claim 151, wherein the bottom surface is further configured as an electrical contact surface.
153. (New) The apparatus according to claim 148, comprising a plurality of first substrate portions, each of said plurality of first substrate portions having one or more light emitting diodes mounted thereon, said plurality of first substrate portions connected to the second substrate portion.
154. (New) The apparatus according to claim 148, further comprising an optical element optically coupled to the plurality of light emitting diodes.
155. (New) The apparatus according to claim 154, wherein the optical element is selected from the group comprising a lens, a holographic film, an array of lenses, an array of lenses and holographic films, an array of holographic films, an optical window and an array of optical windows.
156. (New) The apparatus according to claim 148, wherein the first substrate portion is coated with an optically reflective material.
157. (New) The apparatus according to claim 148, wherein each of the plurality of cups have angled walls, curved walls, square walls or a combination thereof.

158. (New) The apparatus according to claim 148, wherein the plurality of light emitting diodes are comprised of light emitting diodes of different wavelengths.
159. (New) A method of manufacture of an apparatus configured as a light emitting diode light source, the method comprising:
 - a) thermally mounting a plurality of light emitting diodes onto a first substrate portion, said first substrate portion being thermally conductive and electrically conductive;
 - b) electrically connecting each of the plurality of light emitting diodes to the first substrate portion;
 - c) thermally connecting the first substrate portion to a second substrate portion, said second substrate portion being thermally conductive and electrically insulating;
 - d) thermally connecting the second substrate portion to a heat pipe;
 - e) thermally connecting the heat pipe to a heat sink.